

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :
:
In-De OU et al. : Group Art Unit: Unassigned
:
Serial No.: Unassigned : Examiner: Unassigned
:
Filed: February 15, 2002 :



For: **THERMALLY ENHANCED SEMICONDUCTOR BUILD-UP PACKAGE**

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner of Patents
BOX PATENT APPLICATION
Washington, D.C. 20231

Handwritten signature: J. H. Jackson
Handwritten date: 3-2002

Sir:

In compliance with the duty of disclosure under 37 CFR 1.56, and 37 CFR 1.97-1.98, the documents listed on the attached form PTO-1449 are hereby made of record in this patent application. Copies of the listed documents are enclosed.

As this Information Disclosure Statement is being filed prior to the mailing of the first Official Action in this application, no fee is believed due in order to have the enclosed reference considered by the Examiner and made of record in the application.

Early action on the merits of the application is earnestly solicited.

Respectfully submitted,

By:

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